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PATENT
TESSERA 3.3-018 CONT CONT II DIV CONT CONT II

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of :
Khandros et al. : Group Art Unit:
Application No.: Unassigned : Examiner:
Filed: On Even Date Herewith : Date: April 6, 2001
For: MICROELECTRONIC ASSEMBLY :
HAVING ENCAPSULATED WIRE :
BONDING LEADS :
X

BOX PATENT APPLICATION
Commissioner For Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir or Madam:

Preliminary to the initiation of the prosecution of the above-identified pending U.S. patent application, the following amendments and remarks are respectfully submitted.

IN THE TITLE:

Please amend the title of the application to:

--MICROELECTRONIC ASSEMBLY HAVING ENCAPSULATED WIRE BONDING LEADS--.

IN THE SPECIFICATION:

Please insert before the first line, after the title, the following:

CROSS-REFERENCE TO RELATED APPLICATIONS

This is a continuation of United States Patent Application No. 09/488,268, filed January 20, 2000, which is in turn a continuation of United States Patent Application No. 08/984,615, now U.S. Patent No. 6,133,627, which is in turn a

EXPRESS MAIL LABEL NUMBER: EL 756209995 US